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 Local Bus-Latch Capability Flow-Through Architecture Optimizes PCB 	DW OR NT PACKAGE (TOP VIEW)				
Layout	A1 1	7 ₂₄] OEAB			
Center-Pin V _{CC} and GND Configurations	A2 🛮 2	23 B1			
Minimize High-Speed Switching Noise	A3 ∐ 3	22 B2			
 EPIC™ (Enhanced-Performance Implanted 	A4 📙 4	21 📙 B3			
CMOS) 1-μm Process	GND 🛮 5	20 🛭 B4			
• 500-mA Typical Latch-Up Immunity at	GND 🛛 6	19 🛮 V _{CC}			
125°C	GND 🛛 7	18 🛮 V _{CC}			
	GND 🛮 8	17 🛮 B5			
r dokago optiono molado r lactio	A5 🛮 9	16 🛮 B6			
Small-Outline Packages, and Standard Plastic 300-mil DIPs	A6 🛮 10	15 🛮 B7			
riastic sou-iiii Dirs	A7 🛮 11	14 🛮 B8			
description	A8 [12	13 OEBA			

These octal bus transceivers are designed for asynchronous communication between data buses. The control function implementation allows for maximum flexibility in timing.

These devices transmit data from the A bus to the B bus or from the B bus to the A bus depending upon the level at the output-enable (OEAB or OEBA) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives these devices the capability to store data by simultaneous enabling of OEAB and OEBA. Each output reinforces its input in this transceiver configuration. Thus, when both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 in all) will remain at their last states. The 8-bit codes appearing on the two sets of buses will be complementary for the 74AC11623.

The 74AC11623 is characterized for operation from −40°C to 85°C.

FUNCTION TABLE

INP	UTS	OPERATION
OEBA	OEAB	OPERATION
L	L	B data to A bus
Н	Н	A data to B bus
Н	L	Isolation
L	Н	B data to A bus, A data to B bus

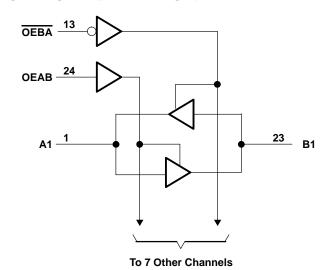
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logic symbol†

OEBA EN1 24 **OEAB** EN2 23 В1 \triangleleft Α1 **▽ 1** \triangleright 2 ▽ 22 **B2 A2** 21 **A3 B3** 20 В4 Α4 17 Α5 **B5** 16 10 **B6** A6 15 11 **B7** Α7 12 14 **B8 A8**

logic diagram (positive logic)



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	\dots -0.5 V to 7 V
Input voltage range, V _I (see Note 1)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V _O (see Note 1)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	$\dots \dots \pm 20 \ mA$
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	$\dots \dots \pm 50 \text{ mA}$
Continuous output current, I_O ($V_O = 0$ to V_{CC})	$\dots \dots \pm 50 \text{ mA}$
Continuous current through V _{CC} or GND pins	$\dots \dots \pm 200 \text{ mA}$
Storage temperature range	-65° C to 150° C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		3	5	5.5	V
		V _{CC} = 3 V	2.1			
V_{IH}	High-level input voltage	$V_{CC} = 4.5 V$	3.15			V
		$V_{CC} = 5.5 V$	3.85			
		V _{CC} = 3 V			0.9	
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$			1.35	V
		$V_{CC} = 5.5 V$			1.65	
٧ _I	Input voltage		0		VCC	V
٧o	Output voltage		0		VCC	V
		V _{CC} = 3 V			-4	
ІОН	High-level output current	$V_{CC} = 4.5 V$			-24	mA
		$V_{CC} = 5.5 V$			-24	
		V _{CC} = 3 V			12	
lOL	Low-level output current	V _{CC} = 4.5 V			24	mA
		$V_{CC} = 5.5 V$			24	
Δt/Δν	Input transition rise or fall rate		0		10	ns/V
TA	Operating free-air temperature		-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	ADAMETED	TEST CONDITIONS	V	T _A = 1		,	MIN	MAX	UNIT
Ρ/	ARAMETER	TEST CONDITIONS	vcc	MIN	TYP	MAX	IVIIIV	WAX	UNIT
				2.9			2.9		
		$I_{OH} = -50 \mu A$	4.5 V	4.4			4.4		
			5.5 V	5.4			5.4		
Vон		I _{OH} = – 4 mA	3 V	2.58			2.48		V
		I _{OH} = – 24 mA		3.94			3.8		
				4.94			4.8		
		I _{OH} = -75 mA [†]	5.5 V				3.85		
						0.1		0.1	
		$I_{OL} = 50 \mu A$	4.5 V			0.1		0.1	
			5.5 V			0.1		0.1	V
VOL		I _{OL} = 12 mA	3 V			0.36		0.44	
			4.5 V			0.36		0.44	
		I _{OL} = 24 mA	5.5 V			0.36		0.44	
		I _{OL} = 75 mA [†]	5.5 V					1.65	
lj	OEBA or OEAB	V _I = V _{CC} or GND	5.5 V			±0.1		±1	μΑ
loz‡	A or B ports	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μΑ
Icc	-	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μΑ
Ci	OEBA or OEAB	V _I = V _{CC} or GND	5 V		4				pF
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12		-		pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

 $[\]ddagger$ For I/O ports, the parameter IOZ includes the input leakage current.



switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T _A = 25°C			MIN	MAX	UNIT
FARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIV	WAA	ONII
t _{PLH}	A or B	B or A	1.5	6.8	9.2	1.5	10.5	ns
t _{PHL}	A of B	D OI A	1.5	6.3	8.2	1.5	9.3	115
^t PZH	OEBA	А	1.5	8	10.6	1.5	12.2	
t _{PZL}		A	1.5	7.9	10.4	1.5	11.6	ns
^t PHZ	OEBA	А	1.5	7	8.7	1.5	9.3	
tPLZ		A	1.5	8	9.9	1.5	10.7	ns
^t PZH	OEAB	В	1.5	8.2	10.4	1.5	12	
t _{PZL}	OEAD	D	1.5	8.3	10.8	1.5	12.2	ns
^t PHZ	OEAB	В	1.5	7	8.8	1.5	9.4	200
^t PLZ	VEAD	D	1.5	8	9.9	1.5	10.6	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

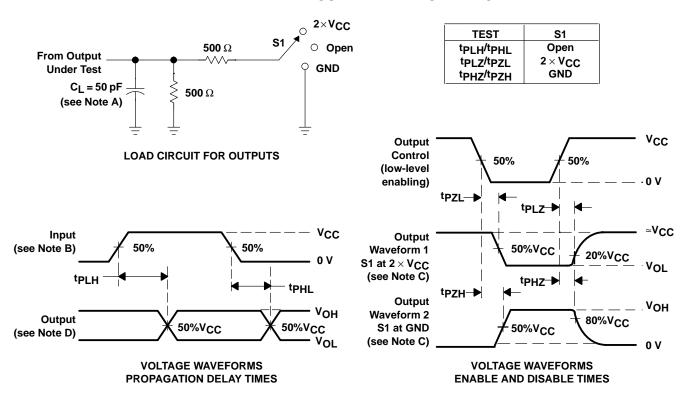
PARAMETER	FROM	то	T _A = 25°C			MIN	MAX	UNIT
PARAIVIETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIN	IVIAA	UNII
^t PLH	A or P	B or A	1.5	4.9	6.8	1.5	7.8	20
^t PHL	A or B	B OF A	1.5	4.6	6.4	1.5	7.1	ns
^t PZH	OEBA	А	1.5	5.8	7.9	1.5	9	ns
^t PZL		۸	1.5	5.9	8.1	1.5	9.1	10
^t PHZ	OEBA	А	1.5	6.1	7.7	1.5	8.3	ns
^t PLZ		٨	1.5	6.6	8.2	1.5	8.8	110
^t PZH	OEAB	В	1.5	6.2	8	1.5	9.2	ns
^t PZL	OEAB	В	1.5	6.1	8.3	1.5	9.4	10
^t PHZ	OEAB	В	1.5	6.2	7.8	1.5	8.3	ns
^t PLZ	OLAB	ט	1.5	6.5	8.1	1.5	8.8	115

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST C	TYP	UNIT		
<u> </u>	Dower discipation conscitance per transciver	Outputs enabled	C 50 pF	f = 1 MHz	49	pF
C _{pd} Power	Power dissipation capacitance per transceiver	Outputs disabled	$C_L = 50 \text{ pF},$	f = 1 MHz	9	p⊢

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns. For testing pulse duration: $t_r = t_f = 1$ to 3 ns. Pulse polarity can be either high-to-low-to-high or low-to-high-to-low.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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